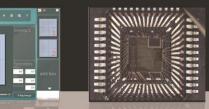
## Radiant Radiant



- Intuitive
- Easy to learn & use
- Start Decaping immediately
- Amazing solutions
- No Damage Wires

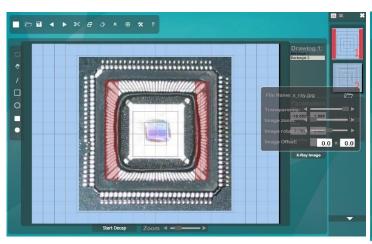
On Copper, Gold, Silver/Gold wires

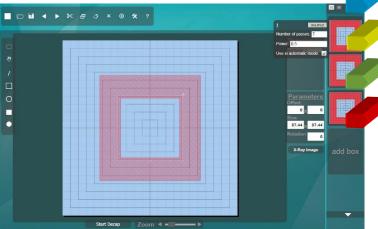
Offers Comprehensive Range of Products & Services that encompass all IC Decapsulation!





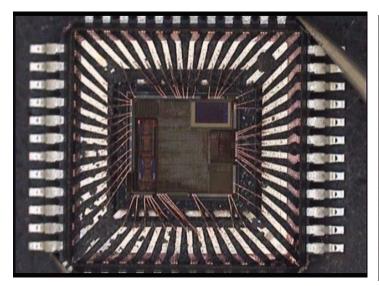
## Extremely User-friendly, Easy to use user interface



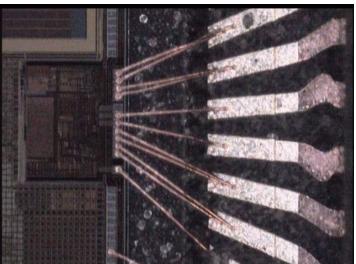


With Life image overlay

Easy to set laser perimeters



Completed After Acid Rinse



Copper Wires still in good

- High power laser system enables the complete decapsulation on IC packages to the exposure of Cu, Al, Au without damaging them.
- High efficient laser enables partial decap to silicon die surface for acid or chemical clean-up operations when post electrical verification required
- Isolated sample room to prevent cross contamination to other equipment parts to improve operational life span
  - High resolution real time video during laser decap process
- Competitive function and cost performance!



World leaders in providing automated decapsulator technology and plastic etching

- \* Using Laser ablation Technology
- \* For Complex Shaped Cavities
- \* It's Repeatable
- \*Consistency in all devises
- \*No Acid needed for 2nd bond
- \*High Laser Safety Features

- \*Intuitive
- \*Easy to learn and use
- \*Start Decaping on the same day it is installed
- \*Overlay Image can be adjusted transparency, image zoom, image rotation & offsets.
- \* No Damage Wires
- \* On Copper, Gold /Silver Wires
- \* Leave100microns of compound on die surface for final acid rinse
- \* No acid rinse on Second bond
- \*Will not damage silver on leadframe & mask on PCB
- \*Smallest cavity at less than 500microns



Laser Details:







High Quality Laser	
Air cooled 1064nm Fiber laser	The Ever Centering chuck has an
Average autout payor 20wett (Castrallable)	

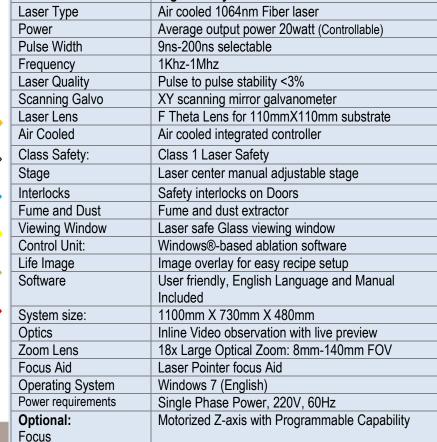
opening of 50mm X 50m

It will always hold the sample at center



All cad templates are defaulted from the center of the chuck







## **Capabilities:**

- -Capable of decapsulating IC packages less than 1mm x 1mm
- -Capable of decapuslating IC packages 10mm or thicker
- -Capable of cutting IC packages
- -Real-time video monitoring
- -High Resolution Camera ≥ 5 Megapixels
- -Camera optical zoom up to 18x
- -Image saving
- -Filtration System
- -Cabinet-Vibration Resistant
- -Compliant with class 10k cleanroom
- -Equipped with HEPA filter with Extra Filter and carbon filter
- -Fume extractor included
- -Positionable exhaust inlet
- -Integrated interface (e.g. power and sleep) or interlock with exhaust/filtration system
- -Installation and Training

